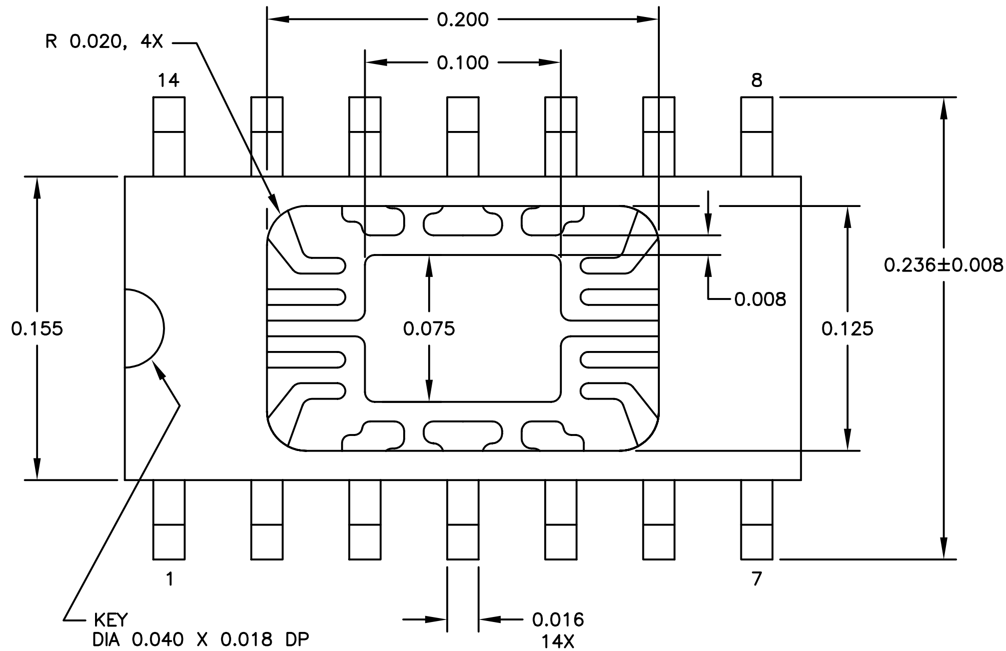
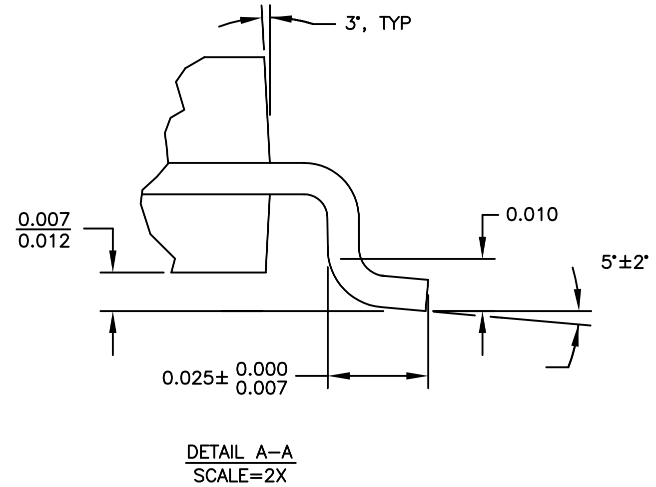
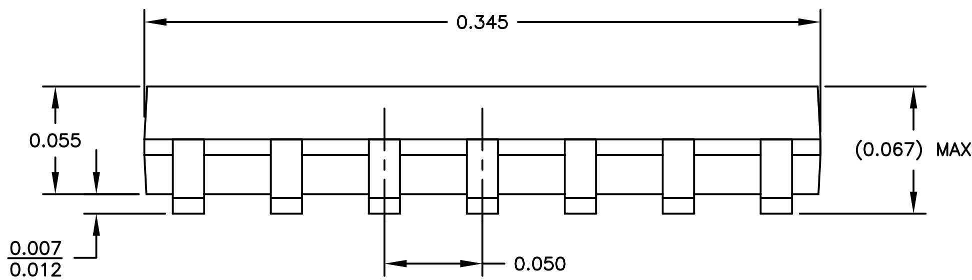
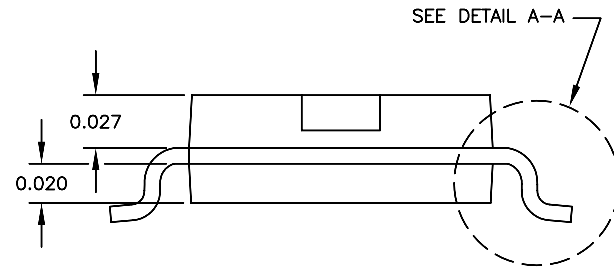
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10507	11/02/05	PRODUCTION RELEASE	D.BENANDO









NOTES:

1. BODY: PLASTIC, SEMICONDUCTOR GRADE
2. LEAD FRAME: COPPER, 194 FH.
3. LEAD FINISH: FULL Au PLATE.
4. FRAME THICKNESS: 0.008"±0.001".
5. DIE PAD: 0.100" X 0.075".
6. JEDEC OUTLINE: MS–012.

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN **INCHES**
TOLERANCES ARE:
X.XX ± 0.01 X.XXXX ±–––
X.XXX ± 0.005 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	11/1/05
APP BY	P. FLASKERUD	DATE	11/1/05
CUSTOMER	–––		

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SEMPAC, INC.
Open-Pak™ Technologies
www.sempac.com
568 E. WEDDELL DRIVE, SUITE 5
SUNNYVALE, CALIFORNIA 94089
PHONE: (408) 400-9002 FAX: (408) 400-9006

14 Lead 150 mils SOIC Open–Pak

SIZE	PART NO.	REV
A	SOIC150–14–OP–01	2

SCALE NONE | CAD FILE SOIC150–14–OP–01–R2.DWG | SHEET 1 OF 1

BORDER–AHI–1.DWG
REV 1 ECN 10598